

**Amendments to the Specification:**

On page 1 please replace the paragraph immediately following the heading RELATED PATENT APPLICATIONS with the following amended paragraph.

(1) (E83-0003), Serial No. 08/239,424, filed May 6, 1994, entitled Composite Bump Structure and Methods of Fabrication assigned to the same assignee, now U.S. Patent No. 5,393,679.

(2) (E83-0004), Serial No. 08/239,380, filed May 6, 1994, entitled Composite Bump Flip Chip Bonding assigned to the same assignee, now U.S. Patent No. 5,431,328.